

Process Menu at MEMS-CORE

item	Process	Material/Equipment
Film deposition	Dielectrics (SiO ₂ , NSG, PSG)	Oxidation furnace, P-TEOS Atmospheric Pressure-CVD
	Metal (Au, Pt, Cr, Ti, Cu, W <i>et al</i>)	Sputtering, EB evaporation, Electro-plating
Photo-lithography	Resist Coat /Bake Exposure	Spin coater, Bake oven, Hot-plate Sus MA6, Double side aligner,
	Photomask making	CAD (CoventorWare™), Pattern generator
Etching	Dry etching (SiO ₂ , Si, Metals)	Deep RIE, RIE, Sacrificial Etching, XeF ₂ Si etching Ion milling, O ₂ plasma asher
	Wet etching	TMAH, HF-NH ₄ F, Metal wet etching
Bonding	Wafer bonding	Anodic bonding, Thermal bonding
Dicing Packaging	Wafer dicing	Blade dicer, Leaser dicer(Stealth)
	Die bonding, Wire bonding	Die bonder, Wire bonder
Polishing	Wafer polishing	Chemical mechanical polisher, Cleaner
Measurement Inspection		Measurement microscope, Leaser microscope, SEM, Stress monitor Sheet resistance, Surface profiler, Optical thickness measurement
Miscellaneous	Cleaning, Surface treatment	UV/O ₃ , HMDS

Foundry service/Collaboration scheme

	Concept	Design	Proto type	Evalua tion	Production	Example
MEMS-CORE original						Acoustic emission sensor
Contracted development				★	★	
Collaboration	★	★		★	★	
Contracted production				★	★	

Operated by



: Customer



: MEMS-CORE



: Case by case

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